

### FEATURES

- Low Switching Losses At High Frequency.
- Fully Characterised For Operation Up To 20kHz.

### APPLICATIONS

- High Power Inverters And Choppers.
- UPS.
- AC Motor Drives.
- Induction Heating.
- Cycloconverters.

### VOLTAGE RATINGS

Type Number	Repetitive Peak Voltages $V_{DRM}$ $V_{RRM}$	Conditions
DK13 08FW K or M DK13 06FW K or M	800 600	$V_{RSM} = V_{RRM} + 100V$ $I_{DRM} = I_{RRM} = 15mA$ at $V_{RRM}$ or $V_{DRM}$ & $T_{vj}$

### ORDERING INFORMATION

When ordering, select the required part number shown in the Voltage Ratings selection table, then:-

Add K to type number for 1/2" 20 UNF thread, e.g. **DK13 06FWK**

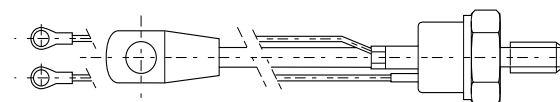
or

Add M to type number for M12 thread, e.g. **DK13 06FM**.

Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order.

### KEY PARAMETERS

$V_{DRM}$	800V
$I_{T(RMS)}$	110A
$I_{TSM}$	1200A
dV/dt	200V/ $\mu s$
dI/dt	200A/ $\mu s$
$t_q$	10 $\mu s$



Outline type code: TO94  
See Package Details for further information.

Fig. 1 Package outline

## CURRENT RATINGS

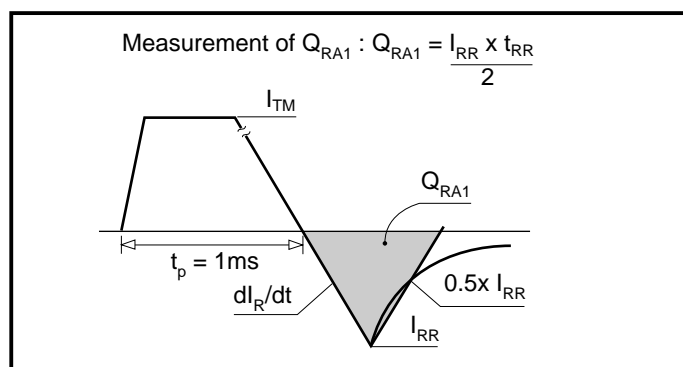
Symbol	Parameter	Conditions	Max.	Units
$I_{T(AV)}$	Mean on-state current	Half wave resistive load, $T_{case} = 80^{\circ}C$	70	A
$I_{T(RMS)}$	RMS value	$T_{case} = 80^{\circ}C$	110	A

## SURGE RATINGS

Symbol	Parameter	Conditions	Max.	Units
$I_{TSM}$	Surge (non-repetitive) on-state current	$t_p = 10ms$ half sine; $T_{case} = 125^{\circ}C$	1.2	kA
$I^2t$	$I^2t$ for fusing	$V_R = 0\% V_{RRM} - 1/4$ sine	$7.2 \times 10^3$	A <sup>2</sup> s

## THERMAL AND MECHANICAL DATA

Symbol	Parameter	Conditions	Min.	Max.	Units
$R_{th(j-c)}$	Thermal resistance - junction to case	dc	-	0.24	$^{\circ}C/W$
$R_{th(c-h)}$	Thermal resistance - case to heatsink	Mounting torque 15.0Nm with mounting compound	-	0.08	$^{\circ}C/W$
$T_{vj}$	Virtual junction temperature	On-state (conducting)	-	125	$^{\circ}C$
		Reverse (blocking)	-	125	$^{\circ}C$
$T_{stg}$	Storage temperature range		-40	150	$^{\circ}C$
-	Mounting torque		12.0	15.0	Nm

MEASUREMENT OF RECOVERED CHARGE -  $Q_{RA1}$ 

## DYNAMIC CHARACTERISTICS

Symbol	Parameter	Conditions		Min.	Max.	Units	
V <sub>TM</sub>	Maximum on-state voltage	At 300A peak, T <sub>case</sub> = 25°C		-	2.35	V	
I <sub>RRM</sub> /I <sub>DRM</sub>	Peak reverse and off-state current	At V <sub>RRM</sub> /V <sub>DRM</sub> , T <sub>case</sub> = 125°C		-	15	mA	
dV/dt	Maximum linear rate of rise of off-state voltage	Linear to 60% V <sub>DRM</sub> T <sub>j</sub> = 125°C, Gate open circuit		-	200	V/μs	
dI/dt	Rate of rise of on-state current	Gate source 20V, 20Ω	Repetitive 50Hz	-	500	A/μs	
		t <sub>r</sub> < 0.5μs, T <sub>j</sub> = 125°C	Non-repetitive	-	800	A/μs	
V <sub>T(TO)</sub>	Threshold voltage	At T <sub>vi</sub> = 125°C		-	1.65	V	
r <sub>T</sub>	On-state slope resistance	At T <sub>vi</sub> = 125°C		-	3.5	mΩ	
t <sub>gd</sub>	Delay time	T <sub>j</sub> = 25°C, I <sub>T</sub> = 50A, V <sub>D</sub> = 300V, I <sub>G</sub> = 1A, dI/dt = 50A/μs, dI <sub>G</sub> /dt = 1A/μs		-	3	μs	
t <sub>(ON)TOT</sub>	Total turn-on time			-	1.5	μs	
I <sub>H</sub>	Holding current	T <sub>j</sub> = 25°C, I <sub>TM</sub> = 1A, V <sub>D</sub> = 12V		60*	-	mA	
t <sub>q</sub>	Turn-off time	T <sub>j</sub> = 125°C, I <sub>T</sub> = 100A, V <sub>R</sub> = 50V, dV/dt = 200V/μs (Linear to 60% V <sub>DRM</sub> ), dI <sub>R</sub> /dt = 30A/μs, Gate open circuit		t <sub>q</sub> code: W	-	10	μs

\*Typical value.

## GATE TRIGGER CHARACTERISTICS AND RATINGS

Symbol	Parameter	Conditions	Typ.	Max.	Units
$V_{GT}$	Gate trigger voltage	$V_{DRM} = 12V$ , $T_{case} = 25^{\circ}C$ , $R_L = 6\Omega$	-	3.0	V
$I_{GT}$	Gate trigger current	$V_{DRM} = 12V$ , $T_{case} = 25^{\circ}C$ , $R_L = 6\Omega$	-	200	mA
$V_{GD}$	Gate non-trigger voltage	At $V_{DRM}$ , $T_{case} = 125^{\circ}C$ , $R_L = 1k\Omega$	-	0.2	V
$V_{RGM}$	Peak reverse gate voltage		-	5.0	V
$I_{FGM}$	Peak forward gate current	Anode positive with respect to cathode	-	4	A
$P_{GM}$	Peak gate power		-	16	W
$P_{G(AV)}$	Mean gate power		-	3.0	W

CURVES

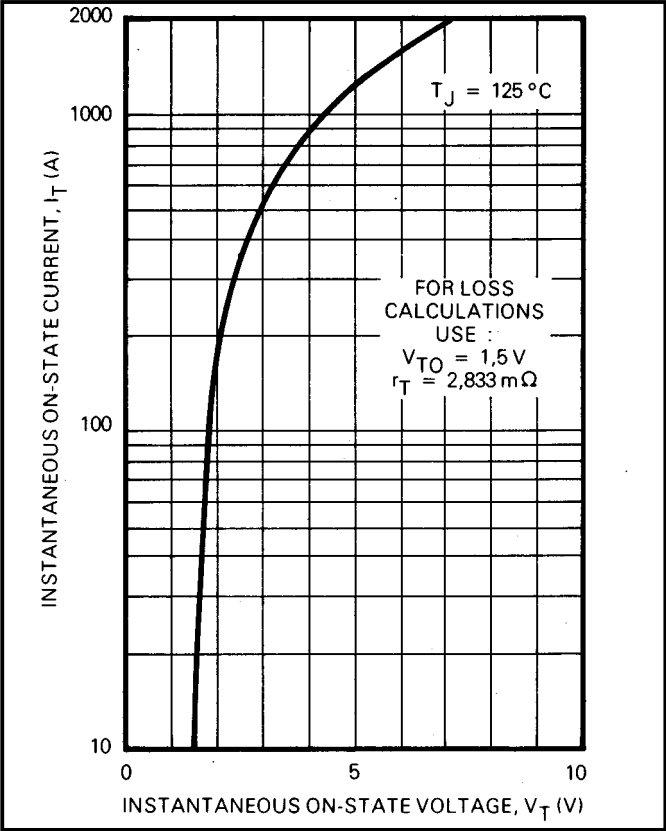


Fig.2 Maximum (limit) on-state characteristics

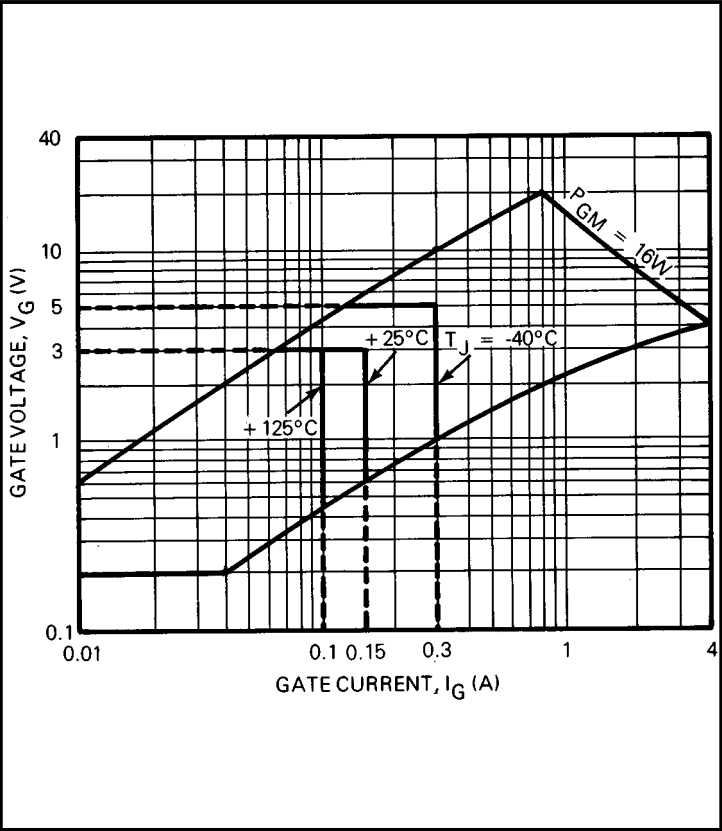


Fig.3 Gate characteristics

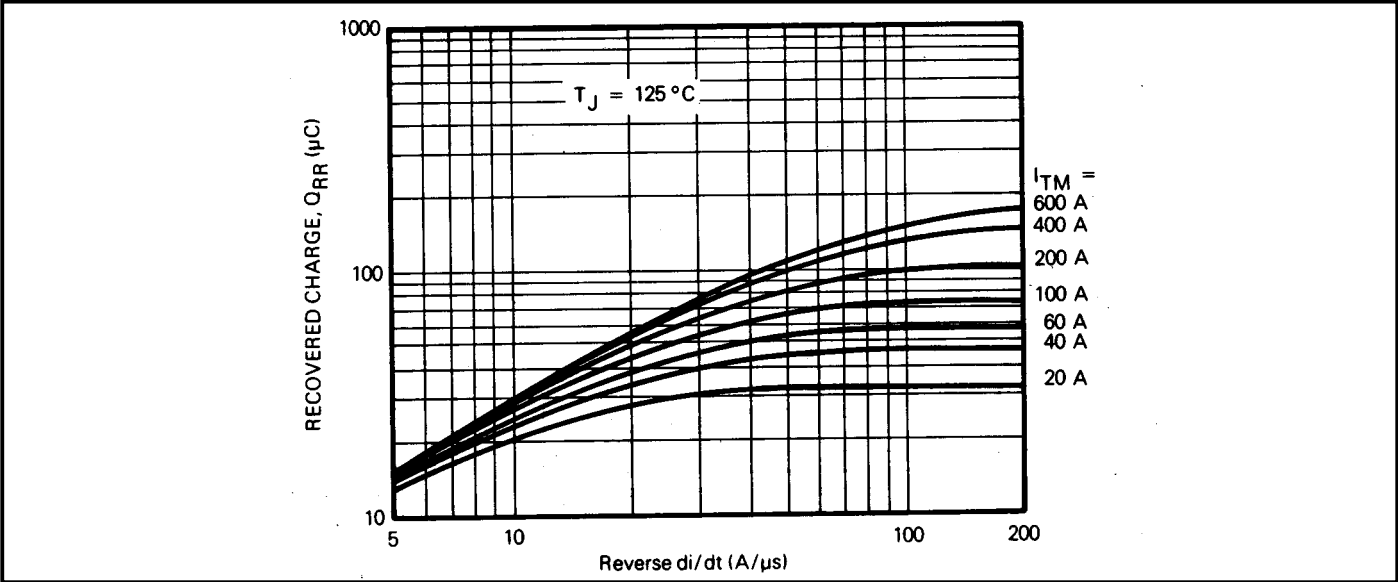
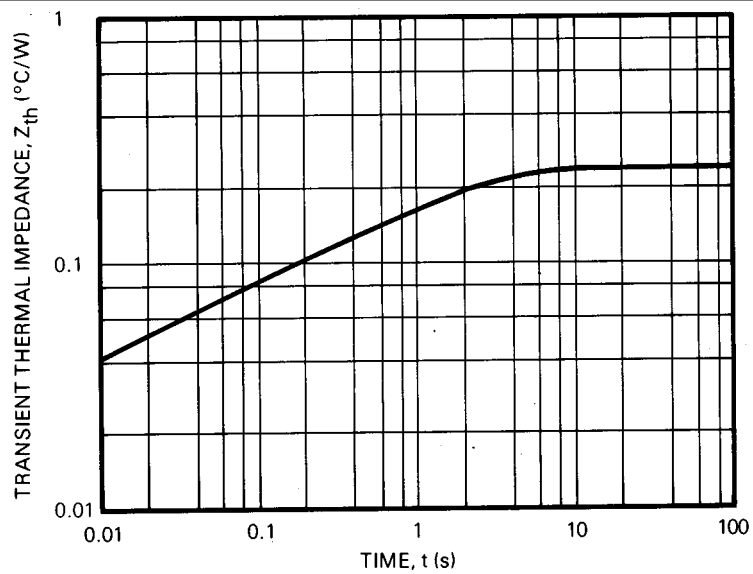
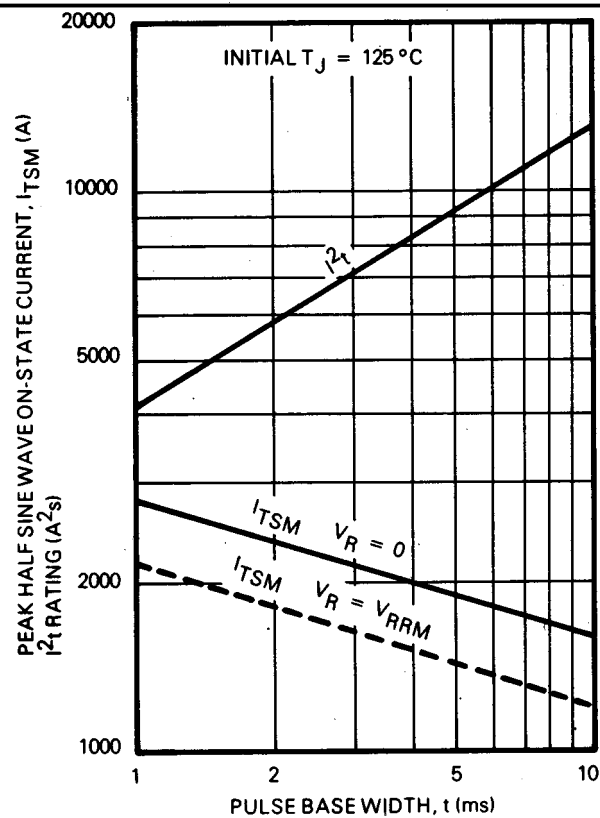


Fig.4 Typical recovered charge (for a device rated  $V_{DRM} = 600\text{ V}$ ,  $t_q = 10\mu\text{s}$ )



**Fig.5 Transient thermal impedance - junction to case**



**Fig.6 Non-repetitive sub-cycle surge on-state current and  $I^2t$  rating**

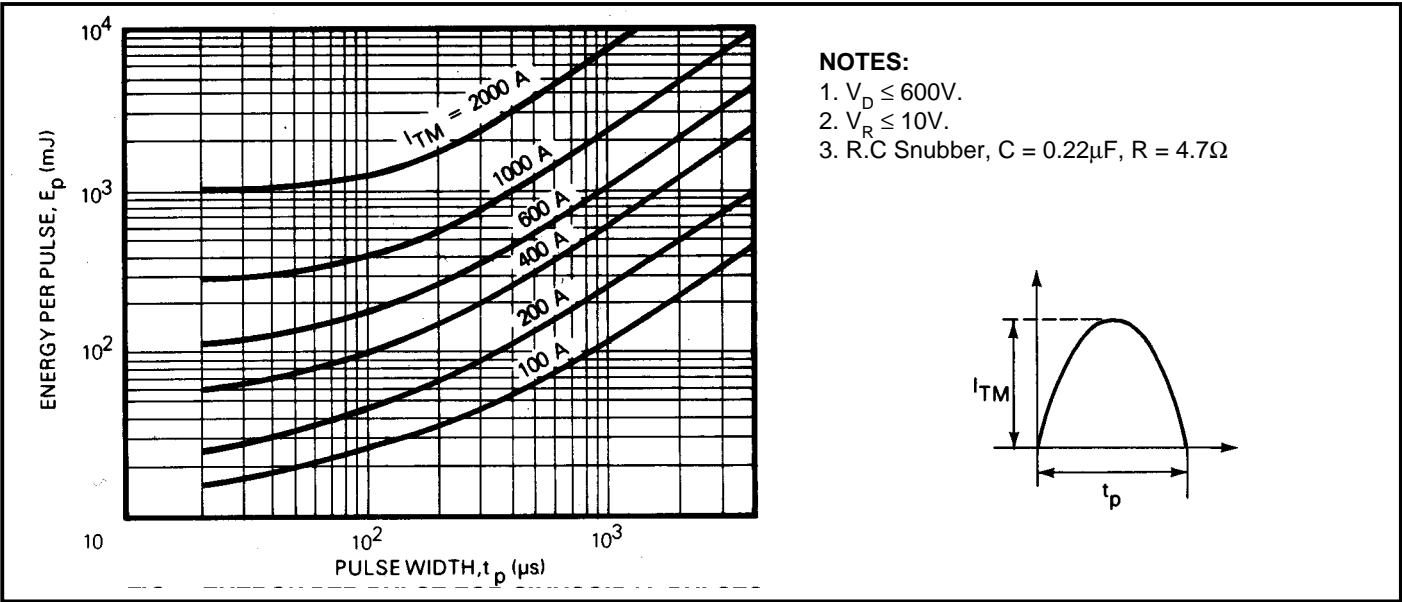


Fig.7 Energy per pulse for sinusoidal pulses

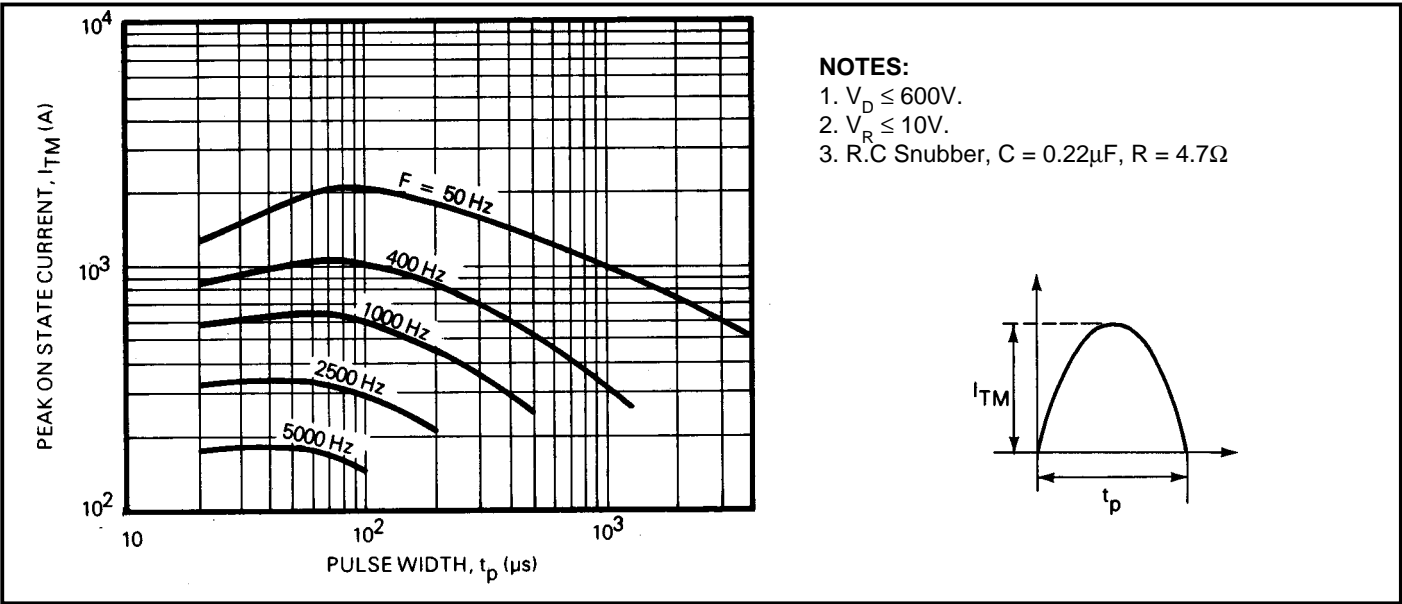
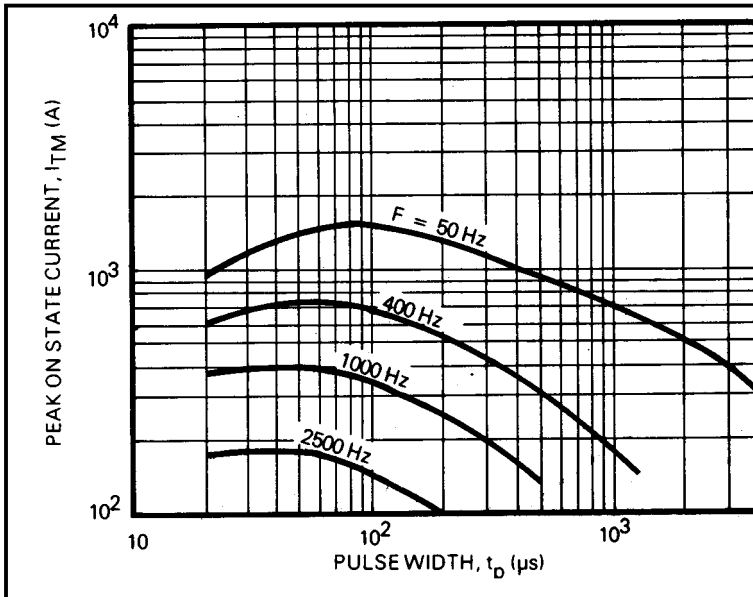
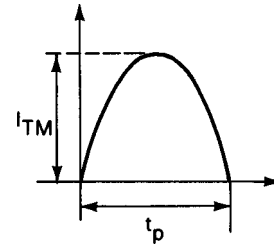


Fig.8 Maximum allowable peak on-state current vs pulse width for  $T_{case} = 65^\circ C$

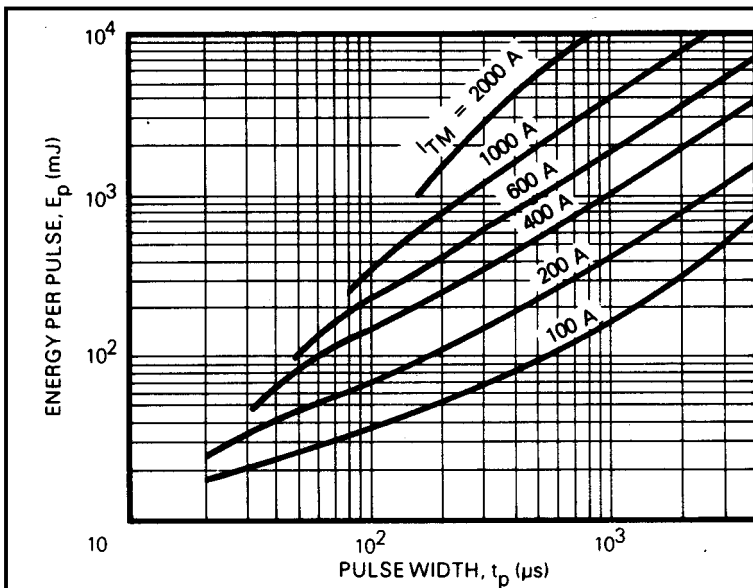


**NOTES:**

1.  $V_D \leq 600V$ .
2.  $V_R \leq 10V$ .
3. R.C Snubber,  $C = 0.22\mu F$ ,  $R = 4.7\Omega$

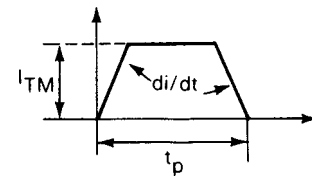


**Fig.9 Maximum allowable peak on-state current vs pulse width for  $T_{case} = 90^\circ C$**

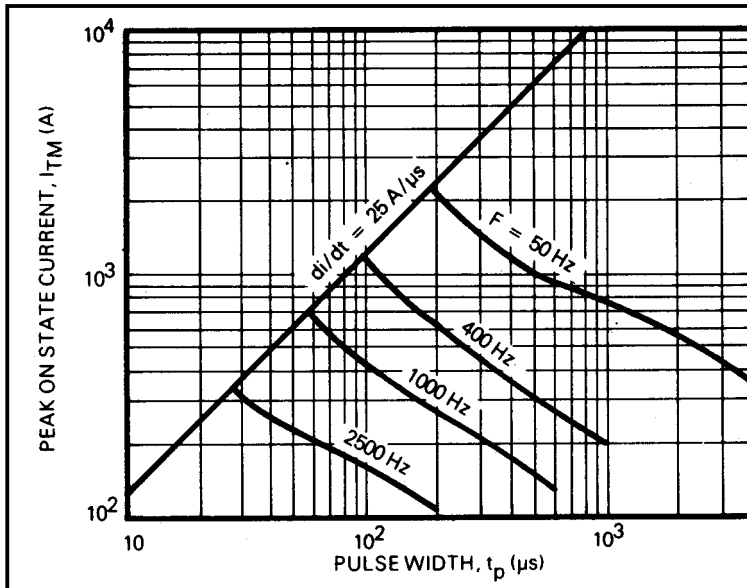


**NOTES:**

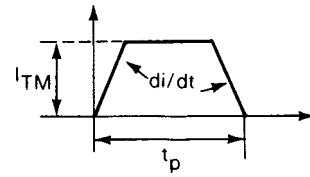
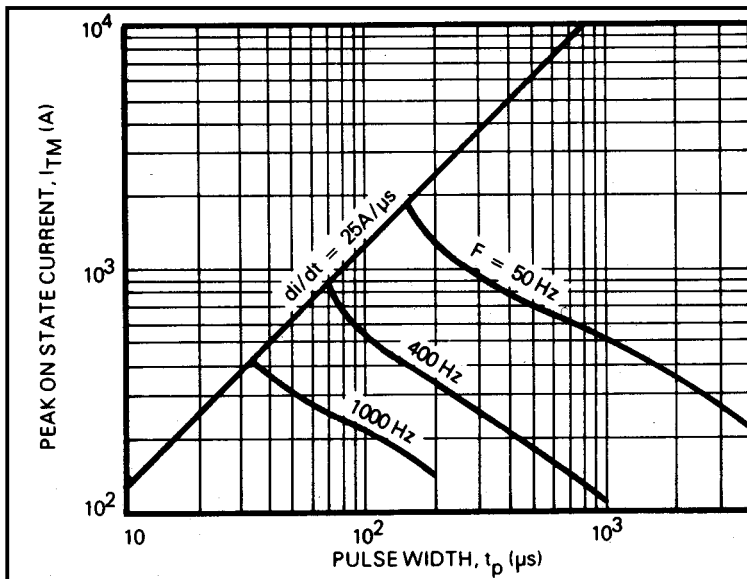
1.  $di/dt = 25A/\mu s$
2.  $V_D \leq 600V$ .
3.  $V_R \leq 10V$ .
4. R.C Snubber,  $C = 0.22\mu F$ ,  $R = 4.7\Omega$



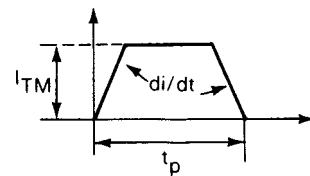
**Fig.10 Energy per pulse for trapezoidal pulses**

**NOTES:**

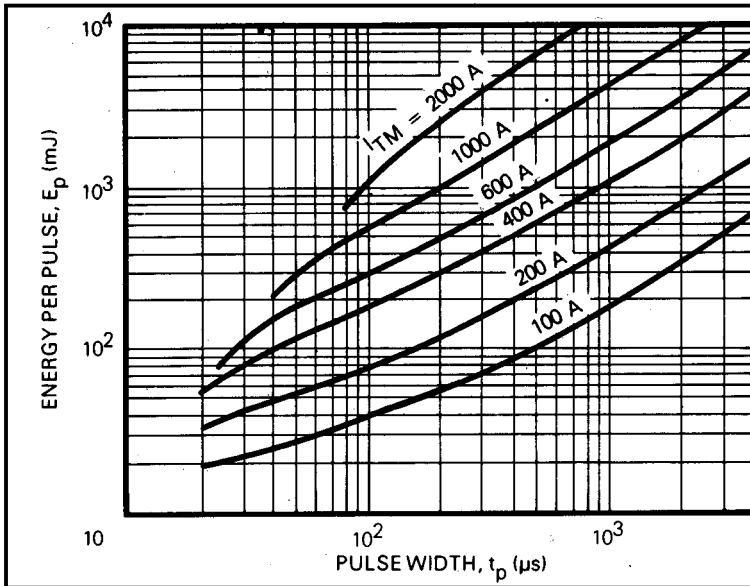
1.  $di/dt = 25 A/\mu s$
2.  $V_D \leq 600V$ .
3.  $V_R \leq 10V$ .
4. R.C Snubber,  $C = 0.22\mu F$ ,  $R = 4.7\Omega$

Fig.11 Maximum allowable peak on-state current vs pulse width for  $T_{case} = 65^\circ C$ **NOTES:**

1.  $di/dt = 25 A/\mu s$
2.  $V_D \leq 600V$ .
3.  $V_R \leq 10V$ .
4. R.C Snubber,  $C = 0.22\mu F$ ,  $R = 4.7\Omega$

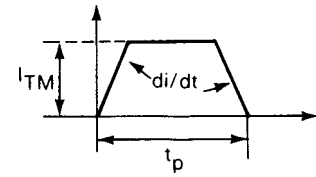
Fig.12 Maximum allowable peak on-state current vs pulse width for  $T_{case} = 90^\circ C$



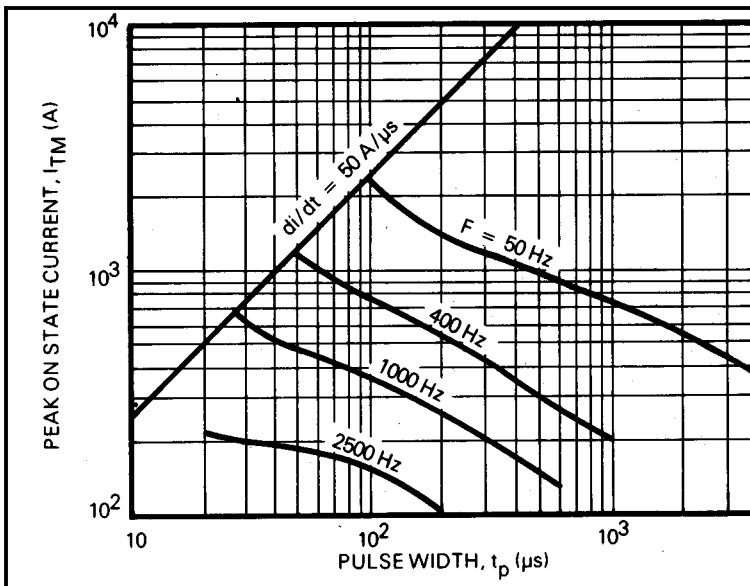


**NOTES:**

1.  $di/dt = 50 \text{ A}/\mu\text{s}$
2.  $V_D \leq 600 \text{ V}$ .
3.  $V_R \leq 10 \text{ V}$ .
4. R.C Snubber,  $C = 0.22 \mu\text{F}$ ,  $R = 4.7 \Omega$

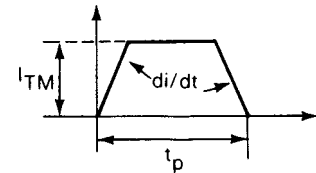


**Fig.13 Energy per pulse for trapezoidal pulses**

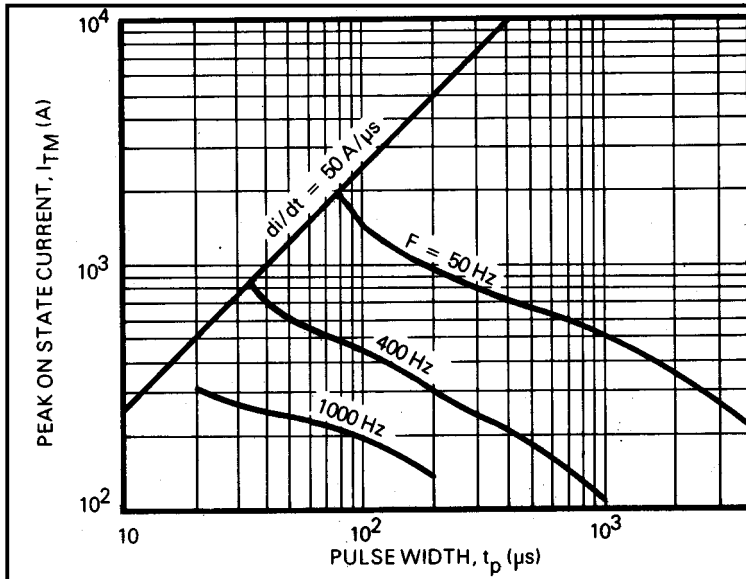


**NOTES:**

1.  $di/dt = 50 \text{ A}/\mu\text{s}$
2.  $V_D \leq 600 \text{ V}$ .
3.  $V_R \leq 10 \text{ V}$ .
4. R.C Snubber,  $C = 0.22 \mu\text{F}$ ,  $R = 4.7 \Omega$



**Fig.14 Maximum allowable peak on-state current vs pulse width for  $T_{\text{case}} = 65^\circ\text{C}$**

**NOTES:**

1.  $di/dt = 50$  A/ $\mu$ s
2.  $V_D \leq 600$  V.
3.  $V_R \leq 10$  V.
4. R.C Snubber,  $C = 0.22$   $\mu$ F,  $R = 4.7$   $\Omega$

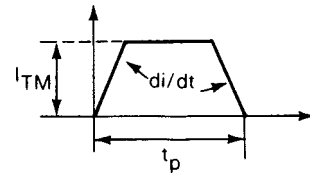
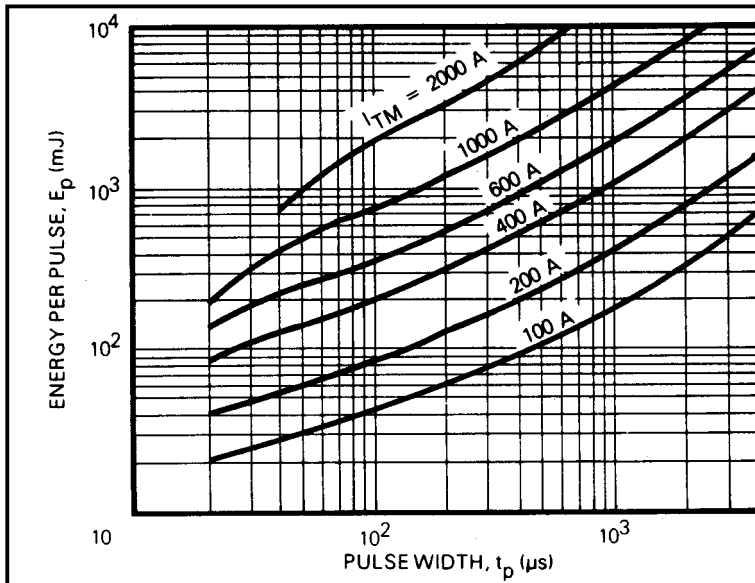


Fig.15 Maximum allowable peak on-state current vs pulse width for  $T_{case} = 65^\circ\text{C}$

**NOTES:**

1.  $di/dt = 100$  A/ $\mu$ s
2.  $V_D \leq 600$  V.
3.  $V_R \leq 10$  V.
4. R.C Snubber,  $C = 0.22$   $\mu$ F,  $R = 4.7$   $\Omega$

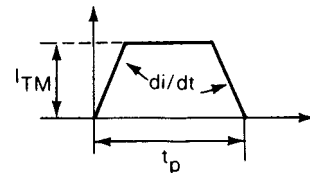
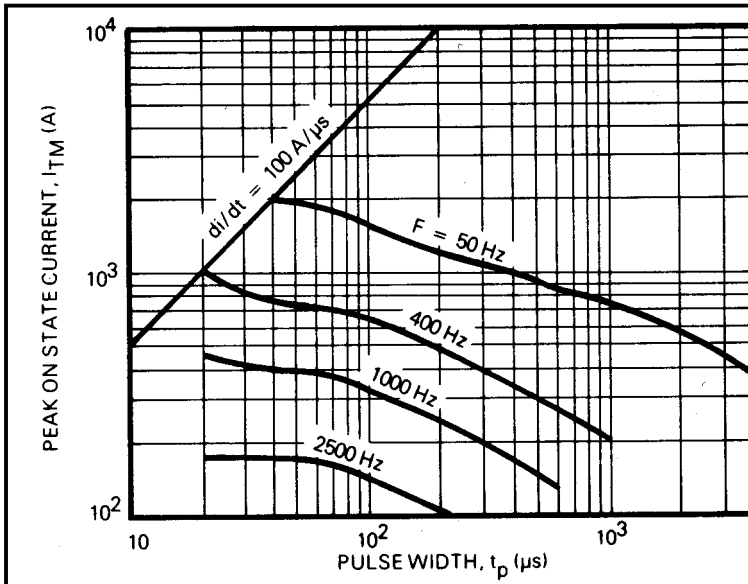
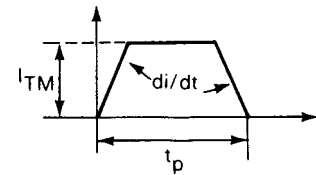


Fig.16 Energy per pulse for trapezoidal pulses

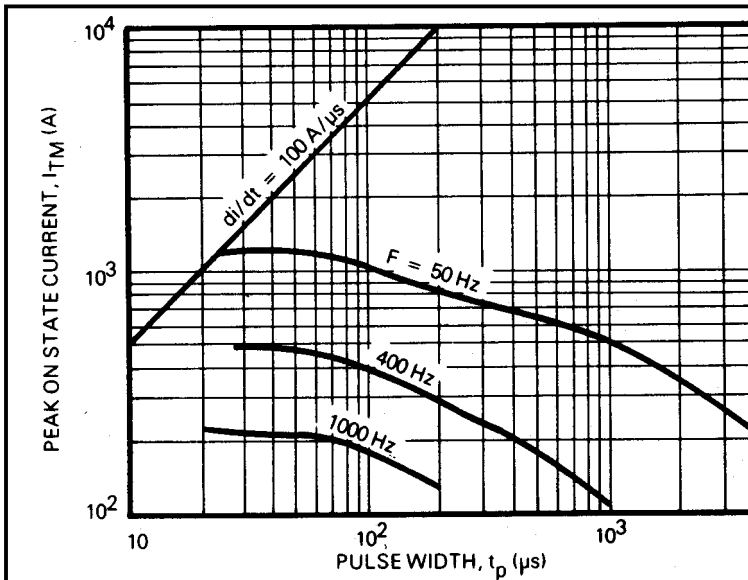


**NOTES:**

1.  $di/dt = 100 A/\mu s$
2.  $V_D \leq 600V$ .
3.  $V_R \leq 10V$ .
4. R.C Snubber,  $C = 0.22\mu F$ ,  $R = 4.7\Omega$

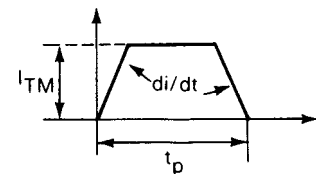


**Fig.17 Maximum allowable peak on-state current vs pulse width for  $T_{case} = 65^\circ C$**



**NOTES:**

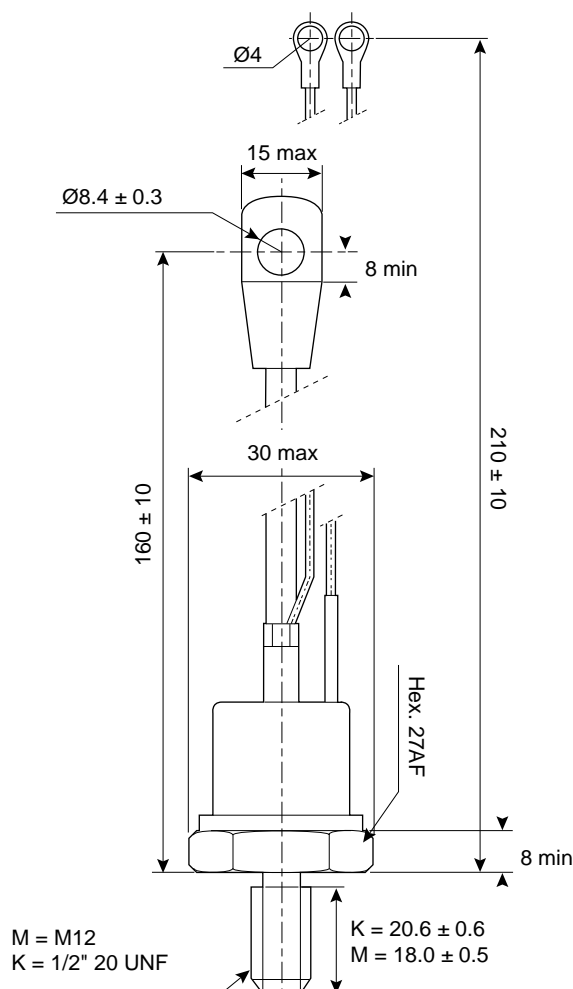
1.  $di/dt = 100 A/\mu s$
2.  $V_D \leq 600V$ .
3.  $V_R \leq 10V$ .
4. R.C Snubber,  $C = 0.22\mu F$ ,  $R = 4.7\Omega$



**Fig.18 Maximum allowable peak on-state current vs pulse width for  $T_{case} = 90^\circ C$**

## PACKAGE DETAILS

For further package information, please contact your nearest Customer Service Centre. All dimensions in mm, unless stated otherwise.  
DO NOT SCALE.



Nominal weight: 120g  
Mounting torque: 15Nm ±10%  
Gate lead colour: White  
Cathode lead colour: Red

Package outline type code: TO94

## POWER ASSEMBLY CAPABILITY

The Power Assembly group was set up to provide a support service for those customers requiring more than the basic semiconductor, and has developed a flexible range of heatsink and clamping systems in line with advances in device voltages and current capability of our semiconductors.

We offer an extensive range of air and liquid cooled assemblies covering the full range of circuit designs in general use today. The Assembly group offers high quality engineering support dedicated to designing new units to satisfy the growing needs of our customers.

Using the latest CAD methods our team of design and applications engineers aim to provide the Power Assembly Complete Solution (PACs).

## HEATSINKS

The Power Assembly group has its own proprietary range of extruded aluminium heatsinks which have been designed to optimise the performance of Dynex semiconductors. Data with respect to air natural, forced air and liquid cooling (with flow rates) is available on request.

For further information on device clamps, heatsinks and assemblies, please contact your nearest sales representative or Customer Services.



<http://www.dynexsemi.com>

**e-mail: [power\\_solutions@dynexsemi.com](mailto:power_solutions@dynexsemi.com)**

HEADQUARTERS OPERATIONS  
**DYNEX SEMICONDUCTOR LTD**  
Doddington Road, Lincoln.  
Lincolnshire. LN6 3LF. United Kingdom.  
Tel: +44-(0)1522-500500  
Fax: +44-(0)1522-500550

CUSTOMER SERVICE  
Tel: +44 (0)1522 502753 / 502901. Fax: +44 (0)1522 500020

SALES OFFICES  
**Benelux, Italy & Switzerland:** Tel: +33 (0)1 64 66 42 17. Fax: +33 (0)1 64 66 42 19.  
**France:** Tel: +33 (0)2 47 55 75 52. Fax: +33 (0)2 47 55 75 59.  
**Germany, Northern Europe, Spain & Rest Of World:** Tel: +44 (0)1522 502753 / 502901.  
Fax: +44 (0)1522 500020  
**North America:** Tel: (440) 259-2060. Fax: (440) 259-2059. Tel: (949) 733-3005. Fax: (949) 733-2986.

These offices are supported by Representatives and Distributors in many countries world-wide.  
© Dynex Semiconductor 2003 TECHNICAL DOCUMENTATION – NOT FOR RESALE. PRODUCED IN UNITED KINGDOM

### Datasheet Annotations:

Dynex Semiconductor annotate datasheets in the top right hand corner of the front page, to indicate product status. The annotations are as follows:-

**Target Information:** This is the most tentative form of information and represents a very preliminary specification. No actual design work on the product has been started.

**Preliminary Information:** The product is in design and development. The datasheet represents the product as it is understood but details may change.

**Advance Information:** The product design is complete and final characterisation for volume production is well in hand.

**No Annotation:** The product parameters are fixed and the product is available to datasheet specification.

This publication is issued to provide information only which (unless agreed by the Company in writing) may not be used, applied or reproduced for any purpose nor form part of any order or contract nor to be regarded as a representation relating to the products or services concerned. No warranty or guarantee express or implied is made regarding the capability, performance or suitability of any product or service. The Company reserves the right to alter without prior notice the specification, design or price of any product or service. Information concerning possible methods of use is provided as a guide only and does not constitute any guarantee that such methods of use will be satisfactory in a specific piece of equipment. It is the user's responsibility to fully determine the performance and suitability of any equipment using such information and to ensure that any publication or data used is up to date and has not been superseded. These products are not suitable for use in any medical products whose failure to perform may result in significant injury or death to the user. All products and materials are sold and services provided subject to the Company's conditions of sale, which are available on request.

All brand names and product names used in this publication are trademarks, registered trademarks or trade names of their respective owners.